

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-------------------------------|---|--------------------------------|
| In Re Application of: |) | |
| |) | |
| Martin, <i>et al.</i> |) | Group Art Unit: To Be Assigned |
| |) | |
| Serial No.: To Be Assigned |) | Examiner: To Be Assigned |
| |) | |
| Filed: May 15, 2001 |) | Docket No. 062002-1751 |
| |) | |
| For: METHOD AND APPARATUS FOR |) | |
| ENERGY ELECTRON ENHANCED |) | |
| ETCHING OR SUBSTRATES IN |) | |
| AND AC OR DC PLASMA |) | |
| ENVIRONMENT |) | |

PRELIMINARY AMENDMENT


Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please enter the following preliminary amendment prior to the examination of the above-identified application.

It is not believed that extensions of time or fees for net addition of claims are required, beyond those which may otherwise be provided for in documents accompanying this paper. However, in the event that additional extensions of time are necessary to allow consideration of this paper, such extensions are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to Deposit Account No. 20-0778.

I hereby certify that this correspondence is being deposited with the United States Postal Service, as first class mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231,
on May 15 2001


Signature - Gloria L. Knox

AMENDMENTS

Please amend the above-identified application as follows:

In The Specification

In accordance with 37 C.F.R. § 1.121, please substitute the following clean copy text for the following paragraph:

In the paragraph that spans page 1, lines 7-16:

This application is a division of U.S. Application Serial No. 08/932,025, entitled 'Method And Apparatus For Low Energy Electron Enhanced Etching of Substrates in an AC or DC Plasma Environment, filed September 17, 1997, which claims priority to and the benefit of the filing date of Provisional Patent Application Serial Nos. 60/026,985, filed September 20, 1996, entitled "APPARATUS AND PROCESS FOR LOW-DAMAGE DRY ETCHING OF INSULATORS BY LOW ENERGY ELECTRON ENHANCED ETCHING IN A DC PLASMA"; 60/026,587, filed September 20, 1996, entitled "APPARATUS AND PROCESS FOR LOW-DAMAGE DRY ETCHING OF INSULATORS BY LOW ENERGY ELECTRON ENHANCED ETCHING IN AN AC PLASMA"; and U.S. Patent Application Serial No. 08/705,902, filed on August 28, 1996 entitled "METHOD AND APPARATUS FOR LOW ENERGY ELECTRON ENHANCED ETCHING OF SUBSTRATES".

In The Claims

In accordance with 37 C.F.R. § 1.121, please cancel claims 1-18.

REMARKS

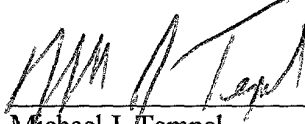
It is hereby respectfully requested that the Examiner enter the Amendment to the above-referenced divisional patent application. Should there be any questions or comments concerning the amendments or remarks referenced herein, the Examiner is respectfully requested to contact the undersigned attorney.

Respectfully submitted,

**THOMAS, KAYDEN,
HORSTEMEYER & RISLEY, L.L.P.**

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By:


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**ANNOTATED VERSION OF MODIFIED SPECIFICATION TO SHOW CHANGES
MADE**

In The Specification

Page 1, line 6, delete "document" and substitute therefor:

--application is a division of U.S. Application Serial No. 08/932,025, entitled 'Method

And Apparatus For Low Energy Electron Enhanced Etching of Substrates in an AC or DC

Plasma Environment, filed September 17, 1997, which--.